

<b>PCN Number:</b>	20150420001	<b>PCN Date:</b>	04/22/2014
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<b>Title:</b>	Datasheet update for TMP112		
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<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
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<b>Change Type:</b>			
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<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process

### PCN Details

**Description of Change:**

Texas Instruments Incorporated is announcing an information only notification etc.

The product datasheet(s) is being updated as summarized below.  
The following change history provides further details.



**TMP112**

SBOS473D – MARCH 2009 – REVISED APRIL 2015

[www.ti.com](http://www.ti.com)

**Changes from Revision C (October 2014) to Revision D**

**Page**

- Changed MIN, TYP, and MAX values for the Temperature Accuracy (temperature error) parameter ..... 5
- Changed the frequency from 2.85 to 3.4 MHz in the POWER SUPPLY section of the *Electrical Characteristics* table ..... 5
- Changed the Temperature Error at 25°C graph in the *Typical Characteristics* section ..... 7
- Changed the Temperature Error vs Temperature graph in the *Typical Characteristics* section ..... 7

**Changes from Revision B (June 2009) to Revision C**

**Page**

- Added *Handling Rating* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section ..... 4
- Changed parameters in *Timing Requirements* ..... 6

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMP112	SBOS473B	<b>SBOS473D</b>

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/tmp112>

**Reason for Change:**

To more accurately reflect device characteristics.

**Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):**

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

**Changes to product identification resulting from this PCN:**

None.

**Product Affected:**

TMP112AIDRLR	TMP112AIDRLT
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>